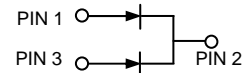
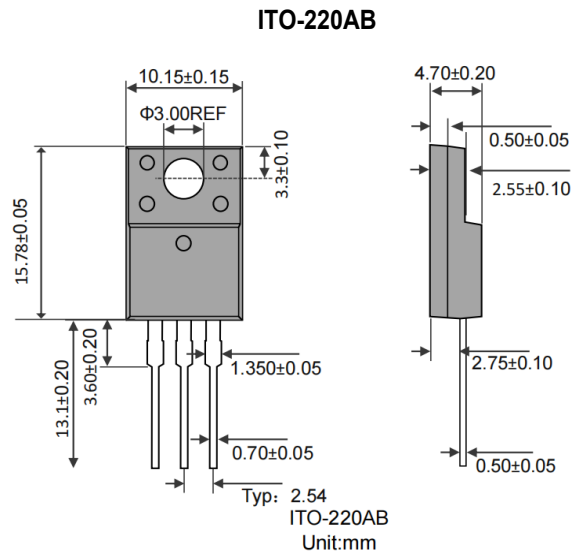


20A HIGH VOLTAGE DUAL SCHOTTKY BARRIER RECTIFIER
Features

- Power Schottky Barrier Chip
- Guard Ring for Transient Protection
- Low Forward Voltage Drop
- Low Power Loss, High Efficiency
- High Surge Current Capability
- Epoxy Meets UL 94V-0 Classification
- Ideally Suited for Use in High Frequency SMPS, Inverters and As Free Wheeling Diodes

Mechanical Data

- Case: ITO-220, Full Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Weight: 1.9 grams (approx.)
- Mounting Position: Any
- Mounting Torque: 0.6 N.m Max.
- **Lead Free: For RoHS / Lead Free Version**


Maximum Ratings and Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	MBR20150FCT	MBR20200FCT	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	150	200	V
Working Peak Reverse Voltage	V_{RWM}			
DC Blocking Voltage	V_R			
RMS Reverse Voltage	$V_{R(RMS)}$	105	140	V
Average Rectified Output Current @ $T_C = 100^{\circ}\text{C}$	I_O	20 10		A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	150		A
Forward Voltage per diode @ $I_F = 10\text{A}$, $T_J = 25^{\circ}\text{C}$ @ $I_F = 10\text{A}$, $T_J = 125^{\circ}\text{C}$	V_{FM}	0.92 0.82		V
Peak Reverse Current At Rated DC Blocking Voltage	I_{RM}	0.2 10		mA
Typical Junction Capacitance (Note 1)	C_J	250		pF
Thermal Resistance Junction to Ambient per diode	R_{JA}	62		$^{\circ}\text{C}/\text{W}$
Thermal Resistance Junction to Case per diode	R_{JC}	4.0		
RMS Isolation Voltage Terminals to Case, $t = 1$ min	V_{ISO}	1500		V
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150		$^{\circ}\text{C}$

Note: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

Fig. 1 Forward Current Derating Curve

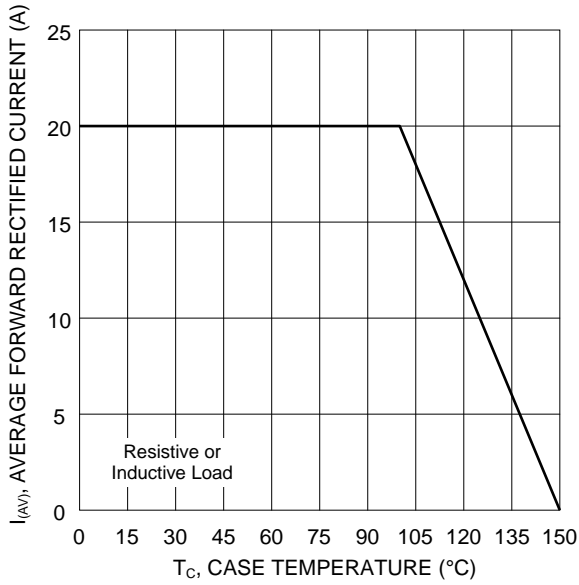


Fig. 2 Typical Forward Characteristics

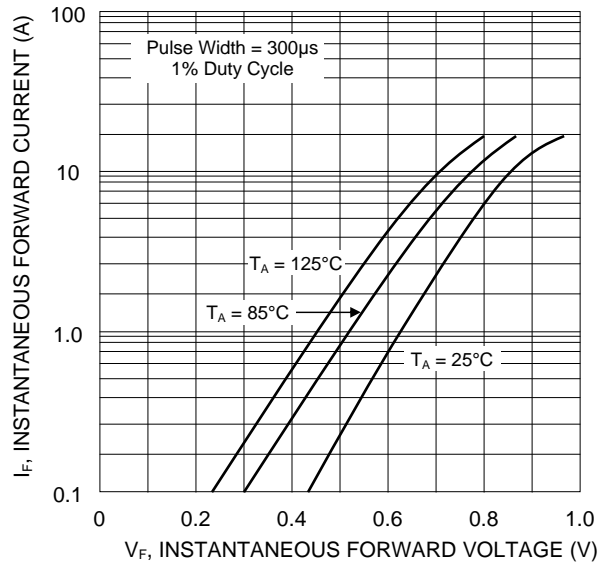


Fig. 3 Forward Surge Current Derating Curve

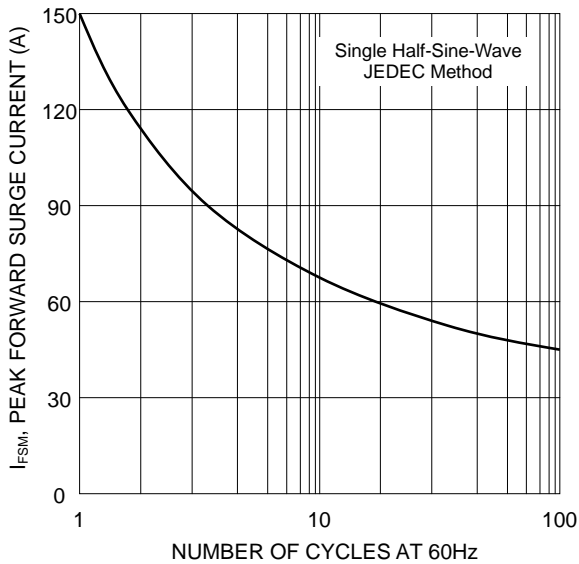


Fig. 4 Typical Reverse Characteristics

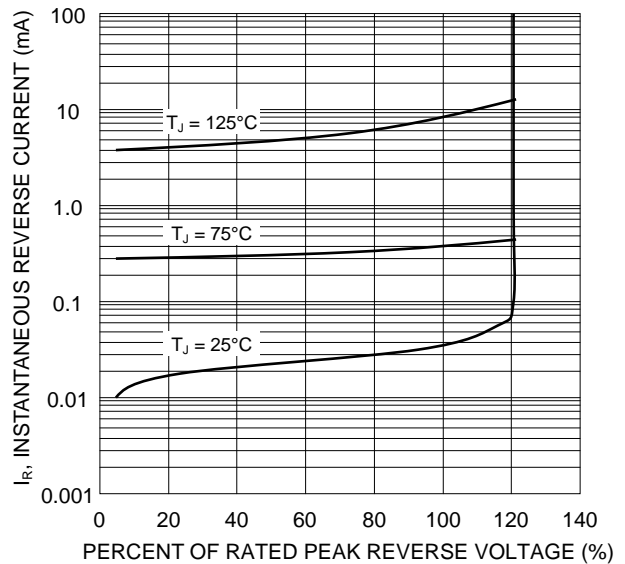


Fig. 5 Forward Power Dissipation

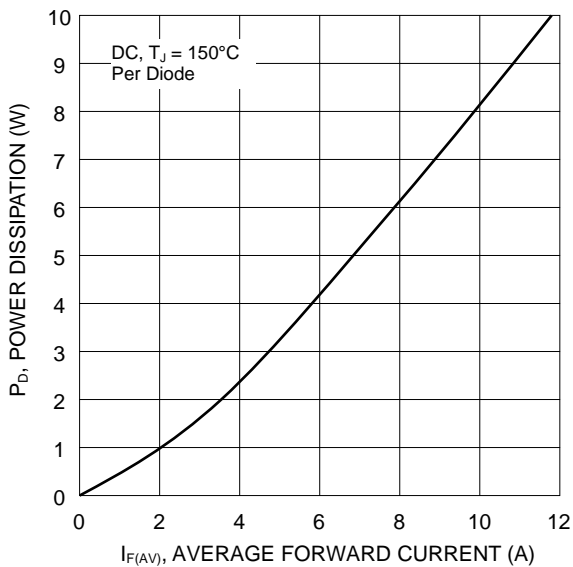
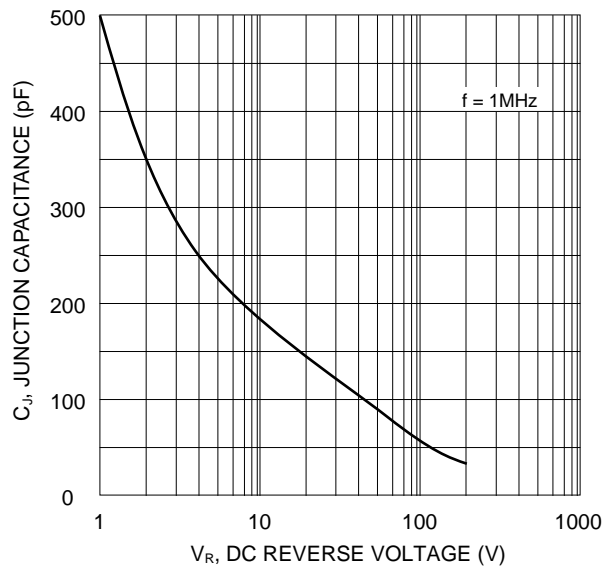
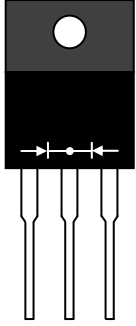


Fig. 6 Typical Junction Capacitance



MARKING INFORMATION



MBR20xxFCT= Device Number
 xx = 150 or 200
 Polarity = As Marked on Body

PACKAGING INFORMATION

BULK

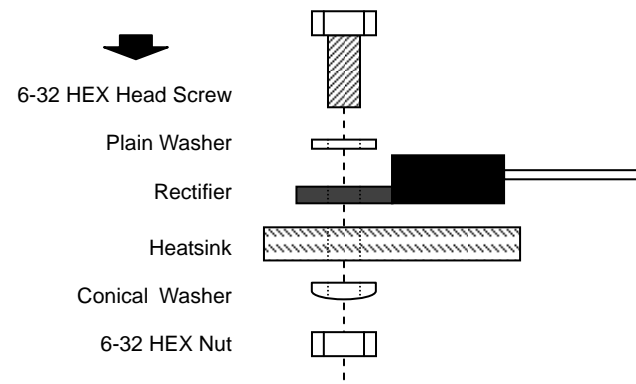
Tube Size L x W x H (mm)	Quantity (PCS)	Inner Box Size L x W x H (mm)	Quantity (PCS)	Carton Size L x W x H (mm)	Quantity (PCS)	Approx. Gross Weight (KG)
525 x 31 x 6	50	558 x 150 x 40	1,000	570 x 235 x 170	5,000	11.85

RECOMMENDED SCREW MOUNTING ARRANGEMENT

The full molded plastic package affords a major reduction of hardware as compared to a standard TO-220 package. However, precautions should be made in mounting procedure.

A conical washer should be used to apply proper force to the device. Screw should not be tightened with any type of air-forced torque or equipment that may cause crack on device package.

A layer of thermal grease or thermal pad in the interface will be considerably helpful for heat dissipation.



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